









Description

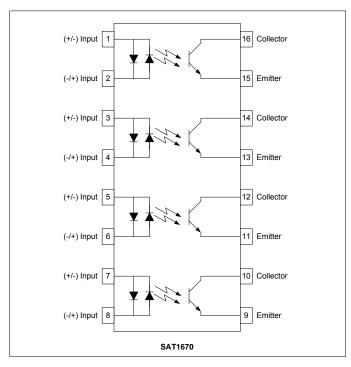
The SAT1670 consists of four phototransistors, each optically coupled to two light emitting diodes. Optical coupling between the input IR LEDs and output phototransistor allows for high isolation levels while maintaining low-level AC or DC signal control capability. The SAT1670 provides an optically isolated method of controlling many interface applications such telecommunications, industrial control and instrumentation circuitry.

The SAT1670 comes standard in an ultra-miniature 16 pin SSOP package.

Applications

- Office Automation Equipment
- System Appliances, Measuring Instruments
- Computer Terminals, PLCs
- Telecom / Datacom
- Home Appliances
- **Digital Logic Inputs**
- Fax / Modems
- **Power Supplies**

Schematic Diagram



Features

- Ultra miniature 16 pin SSOP package
- Low input power consumption
- High stability
- CTR Range 20 400%
- High Isolation Voltage (3750V_{RMS})
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL/C-UL: File # E201932

VDF: File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature	55 to +125°C
Operating Temperature	40 to +100°C
Continuous Input Current	50mA
Transient Input Current	500mA
Reverse Input Control Voltage	6V
Input Power Dissipation	
Total Power Dissipation	600mW
Solder Temperature – Wave (10sec)	260°C
Solder Temperature - IR Reflow (10sec)	260°C

Ordering Information

Part Number Description

SAT1670 16 pin SSOP

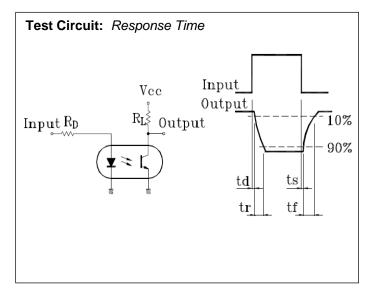
SAT1670-TR 16 pin SSOP, Tape and Reel (2000/Reel)

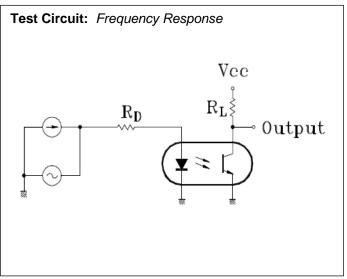
NOTE: Suffixes listed above are not included in marking on device for part number identification



Electrical Characteristics, T_A = 25°C (unless otherwise specified)

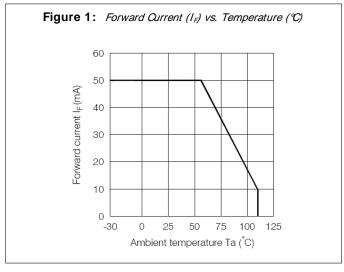
Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions	
Input Specifications							
LED Forward Voltage	V _F	-	1.2	1.4	V	I _F = ±20mA	
Terminal Capacitance	Ct	-	60	250	pF	V=0, f=1KHz	
Output Specifications							
Collector-Emitter Voltage	V _{CEO}	80	-	-	V	Ι _C =100μΑ	
Emitter-Collector Voltage	V _{COE}	7	-	-	V	I _E =10μA	
Collector Dark Current	I _{CEO}	-	-	100	nA	V _{CE} =50V, I _F =0mA	
Floating Capacitance	C _f	-	0.8	1.0	pF	V=0, f=1MHz	
Cut-Off Frequency	f _C	-	80	-	kHz	V _{CE} =2V, I _C =20mA, R _L =100Ω, -3dB	
Saturation Voltage	V _{CE(sat)}	-	0.1	0.4	V	I _F =±20mA, I _C =1mA	
Coupled Specifications							
Rise Time	T _R	-	3	-	μS	$I_C=\pm 2mA$, $V_{CC}=2V$, $R_L=100\Omega$	
Fall Time	T _F	-	4	-	μS	$I_C=\pm 2mA$, $V_{CC}=2V$, $R_L=100\Omega$	
Current Transfer Ratio	CTR	20	-	400	%	I _F =±1mA, V _{CE} =5V	
Isolation Specifications							
Isolation Voltage	V _{ISO}	3,750	-	-	V_{RMS}	RH ≤ 50%, t=1min	
Input-Output Resistance	R _{I-O}	-	10 ¹²	-	Ω	V _{I-O} = 500V _{DC}	

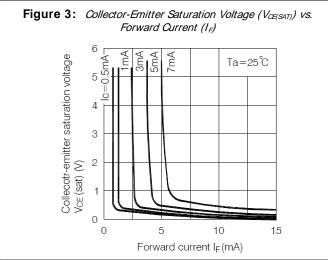


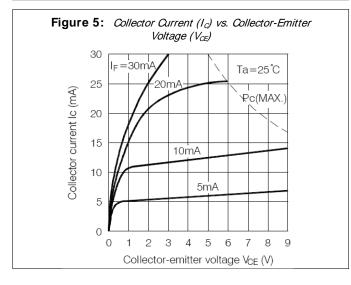


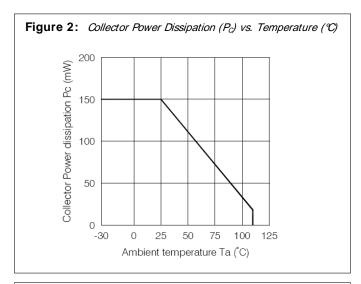


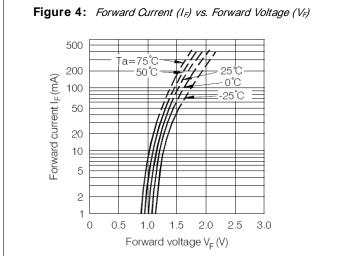
SAT1670 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

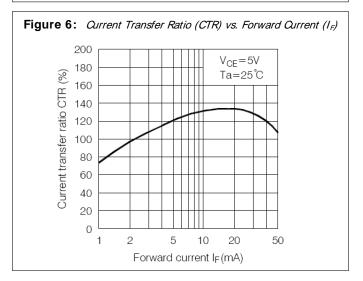






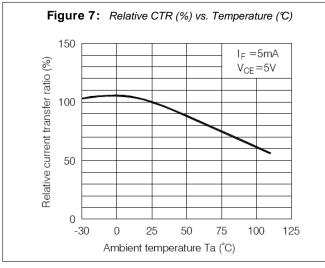


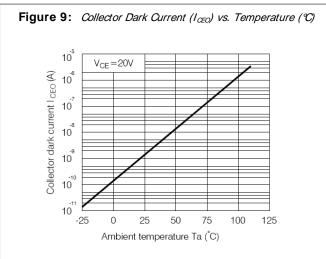


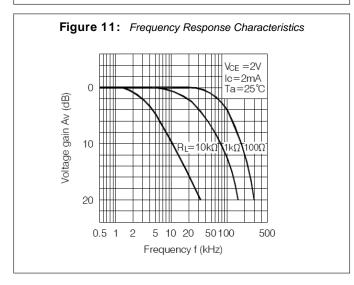


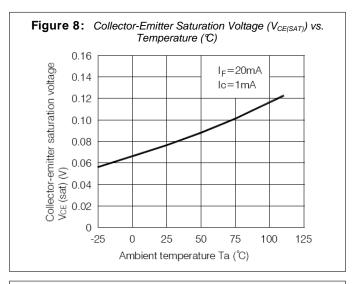


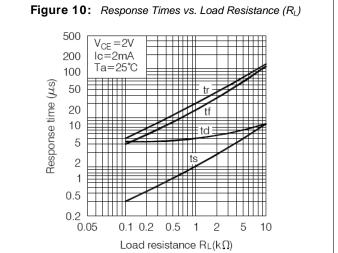
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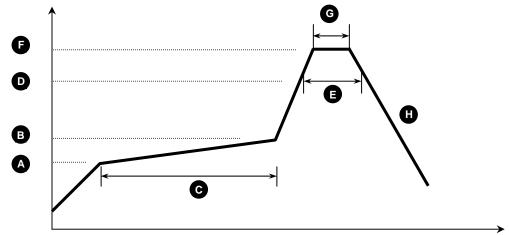




SAT1670 Solder Reflow Temperature Profile Recommendations

(1) Infrared Reflow:

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:



Process Step	Description	Parameter		
Α	Preheat Start Temperature (°C)	150°C		
В	Preheat Finish Temperature (°C)	180°C		
С	Preheat Time (s)	90 - 120s		
D	Melting Temperature (°C)	230°C		
E	Time above Melting Temperature (s)	30s		
F	Peak Temperature, at Terminal (°C)	260°C		
G	Dwell Time at Peak Temperature (s)	10s		
Н	Cool-down (°C/s)	<6°C/s		

(2) Wave Solder:

Maximum Temperature: 260°C (at terminal)

Maximum Time: 10s

Pre-heating: 100 - 150°C (30 - 90s)

Single Occurrence

(3) Hand Solder:

Maximum Temperature: 350°C (at tip of soldering iron)

Maximum Time:

Single Occurrence

3s

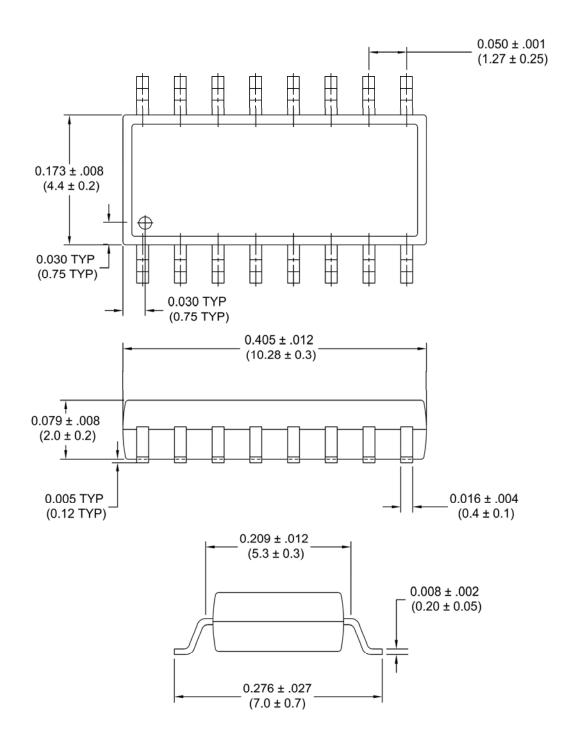
AC Input



SAT1670 Package Dimensions

16 PIN SSOP Package

Note: All dimensions in inches ("), with millimeters [mm] in parentheses

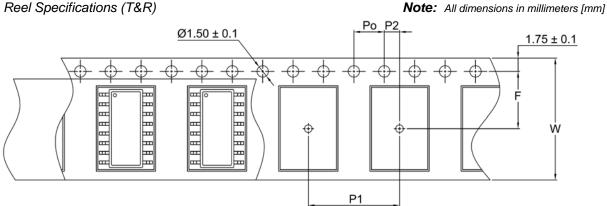


AC Input

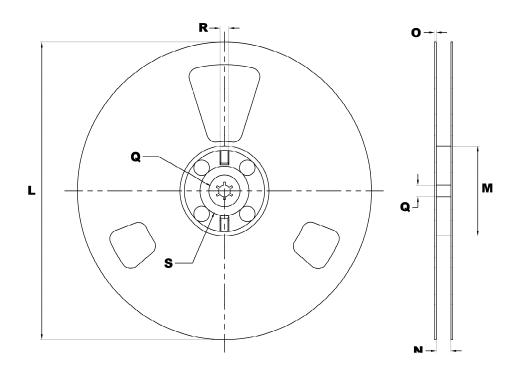


SAT1670 Packaging Specifications

Tape & Reel Specifications (T&R)



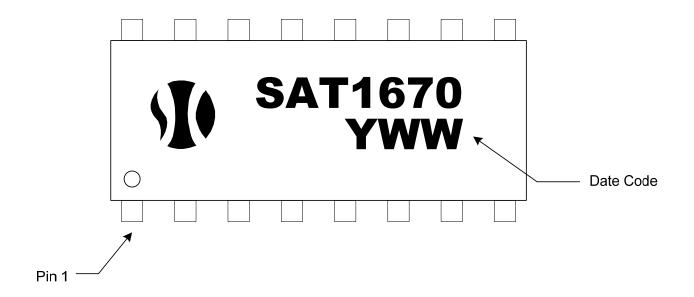
Specification	Symbol Dimensions, mm (i	
Tape Width	W	16 \pm 0.3 (0.63)
Sprocket Hole Pitch	P0	4 ± 0.1 (0.16)
Compartment Location	F P2	7.5 ± 0.1 (0.295) 2 ± 0.1 (0.079)
Compartment Pitch	P1	12 ± 0.1 (0.472)



L	M	N	0	Q	R	S
330±2	101.6±1	16.4+0.2	2.0±0.2	R13±0.5	1.50±0.5	R10±1



SAT1670 Package Marking



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